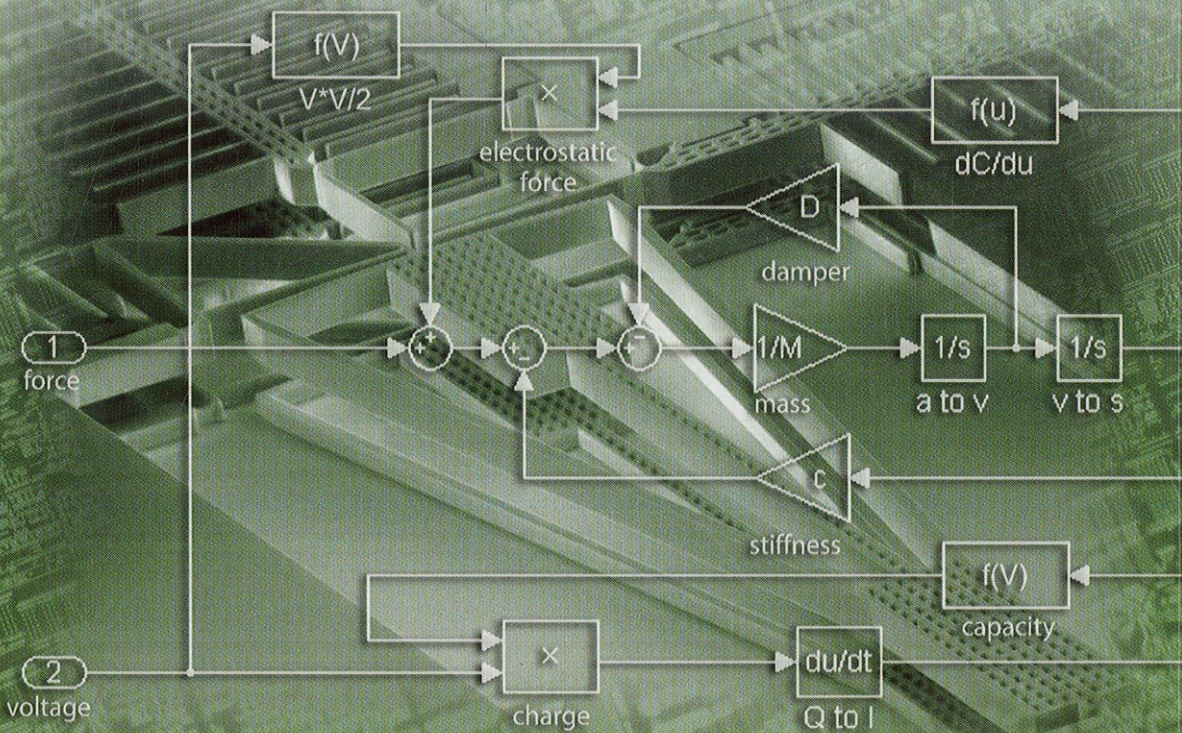


Introduction to

Microsystem Technology

A Guide for Students



Companion Website

 WILEY

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